



## Material Content Data Sheet



<b>Sales Product Name</b>				IPD040N03L G		<b>Issued</b>		25. September 2017	
<b>MA#</b>				MA000655936					
<b>Package</b>				PG-TO252-3-311		<b>Weight*</b>		317.11 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.734	0.55	0.55	5469	5469	
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		452		
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136		
	non noble metal	copper	7440-50-8	143.098	45.12	45.18	451259	451847	
wire	non noble metal	aluminium	7429-90-5	0.032	0.01	0.01	100	100	
encapsulation	organic material	carbon black	1333-86-4	0.324	0.10		1022		
	plastics	epoxy resin	-	19.556	6.17		61670		
	inorganic material	silicondioxide	60676-86-0	127.379	40.17	46.44	401689	464381	
leadfinish	non noble metal	tin	7440-31-5	3.740	1.18	1.18	11794	11794	
plating	non noble metal	nickel	7440-02-0	0.086	0.03		273		
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	274	
solder	noble metal	silver	7440-22-4	0.044	0.01		139		
	non noble metal	tin	7440-31-5	0.035	0.01		112		
	non noble metal	lead	7439-92-1	1.690	0.53	0.55	5329	5580	
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61		
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18		
	non noble metal	copper	7440-50-8	19.177	6.05	6.06	60476	60555	
*deviation	< 10%					Sum in total:	100.00	1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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